



AURUNA® 8400 Gold Nickel Electrolyte

High speed electrolyte for hard gold plating

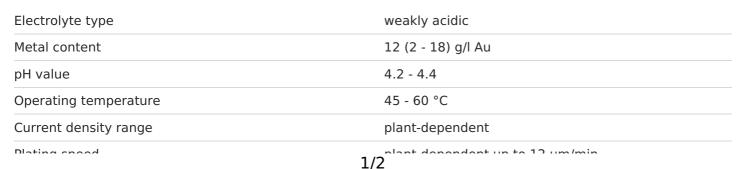
AURUNA® 8400 is used for the deposition of hard gold coatings in special high-speed equipment. The electrolyte is weakly acidic, citrate-free and has a wide working range with simple bath maintenance.

The deposited coatings are high-brightness, low-porosity, solderable, hard and abrasion-resistant, and exhibit consistently low contact resistance. They are therefore ideally suited for electrical components such as contacts, plugs and connectors on printed circuit boards.

AURUNA® 8400 was developed for high-speed gold plating in selective plating lines and continuous reel-to-reel systems. It shows stable long-term behavior even with strong electrolyte movement (flow, spray) and high current densities. AURUNA® 8400 can also be used as a pregold electrolyte.

The optional use of AURUNA® Inhibitor 2 offers the possibility of reduced gold consumption of up to 15%. The inhibitor results in sharp edge delineations - thus reducing the run-out zone width. Of course, the coating properties remain unaffected. The inhibitor can be removed without residue after coating by activated carbon cleaning.

Electrolyte characteristics





Pt/Ti (PLATINODE® Pt/Ti) or MMO 177

Coating characteristics

Coating	Gold nickel
Purity	approx. 99.7 wt.% Au, approx. 0.3 wt.% Ni
Colour of deposit	yellow
Brightness	bright to highly bright
Hardness of deposit	approx. 130 - 190 HV
Max. coating thickness	10 μm
Density of the coating	approx. 17 g/cm³

Advantages

- Very high plating speeds
- Lower gold content possible
- Exceptionally wide working range
- Stable long-term behavior
- Easy electrolyte maintenance
- Excellent coating properties

Applications

- Connectors
- Electrical contacts
- Connector strips on printed circuit boards

Your contact person



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